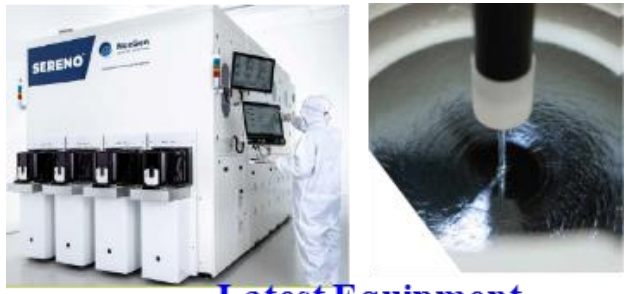
NexGen Wafer Systems Japan LLC

High precision single wafer wet etching and clean equipment business installation into Japanese semiconductor manufacturing

Purpose of the Project

- The purpose of this project is to introduce into Japan high-precision single wafer wet etching equipment developed and manufactured in Austria, and to promote direct investment, revitalize the local economy, and strengthen the supply chain through the establishment of necessary service bases.
- NexGen is headquartered in Singapore and has R&D and equipment manufacturing plants in Austria; consequently, its activities have traditionally been centered in Europe, the United States, Southeast Asia, and China. Due to this geographical constraint, the company had previously been unable to introduce its technology and equipment to the Japanese semiconductor manufacturing industry. However, in response to the expansion of capital investment in the industry, driven by the recent government support, NexGen has decided to expand its business into the Japanese market.
- The technology developed by NexGen is unique and can be differentiated in terms of the control accuracy of Total Thickness Variation (TTV). We believe that it can contribute to the future development of the Japanese semiconductor manufacturing industry.
- We are a company that owns innovative technologies related to the substrate thinning and TTV control for substrate thickness uniformity, which are ones of the important technologies in semiconductor manufacturing.



Latest Equipment

Details of Demonstration

- Since we are a corporation established in 2025, we did not have information on target customers with whom to demonstrate our technology. Consequently, as we needed a sales partner company to carry out sales activities, we signed a partnership agreement with Kanematsu PWS Co., Ltd., a technology trading company, and began collaborative sales activities.
- In parallel with the establishment of the Japanese subsidiary in February 2025, the selection and contracting of sales partners were completed, and domestic marketing activities began. In addition, we showcased our technologies and equipment by exhibiting at the MEF2025 in April, the Japan Society of Applied Physics (JSAP) meeting in September, and SEMICON Japan in December.
- To launch the demonstration phase, we compiled a target company list with the cooperation of the sales partner, and initiated marketing activities in Japan. We prepared our technical presentation materials, flyers, posters, Japanese-language websites, etc., and introduced our technologies and equipment through face-to-face meetings during customer visits and web conferences. Since May 2025, we have held 36 business meetings with customers.

Poster and Exhibit Display at the JSAP Conference

Semicon Japan 25 booth

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Project Outcome

- We introduced our technology and equipment to the Japanese semiconductor manufacturing industry. Of the 94 target customers, we made contact with 72 companies and provided detailed presentations to 36 of them. As a result, we were able to generate 14 sales leads (inquiries from customers regarding equipment purchases) and 9 sales deals (sales leads have progressed to system proposals and requests for cost estimates). In addition, we conducted two equipment demonstration evaluations, both of which yielded favorable results. Through these outcomes, we believe that we have been able to demonstrate the potential of our technology and equipment to fully apply and contribute to the Japanese semiconductor manufacturing industry.
- Based on the results of this activity, we formulated our future business strategies. The results of technology matching for each market segment and their priorities were examined and summarized in the table below. "Yes" in the table indicates that our proprietary technologies can be applied to customer requirements.

Segment Priority	Segmant	Technology Matching					
		Application1	Application2	Application3	Application4	Application5	Application6
1	Segment1	Yes	Yes	Yes		Yes	Yes
2	Segment2		Yes				
3	Segment3		Yes				Yes
4	Segment4		Yes		Yes		
5	Segment5		Yes				
6	Segment6						

Challenges and Solutions

- Currently, the semiconductor market is strong, driven by demand for AI applications, but this is limited to some manufacturers in the advanced logic, memory, and advanced packaging sectors, and automotive semiconductor and power semiconductor manufacturers are still in a difficult situation. In addition, the current depreciation of the yen has led to a significant rise in the yen-denominated prices of imported equipment, and the soaring costs of materials, components, and labor have also raised equipment prices, so the business environment continues to be very difficult for overseas manufacturers. In order to survive under these circumstances, we are committed to implementing initiatives such as reducing costs and further enhancing our technology.

Future Plans

- Future Investment Plan: As soon as equipment orders are confirmed, we plan to open offices as service sites and start hiring FSEs.
- Business Model Introduction: The results of this marketing activity will be used in future business models (including strategies and execution plans).
- Monetization Outlook: If our equipment sales target for FY2026 is achieved, we expect to attain profitability starting in FY2027.